



## Product / Process Change Notice

No.: Z200-PCN-DM201912-07-A

Date: December 30, 2019

**Change Title : W25Q64JW “J-Series” (F58) to replace W25Q64FW “F-Series” (F58) 64Mb 1.8V SpiFlash® Memories**

Change Classification:  Major  Minor with customer notification  Minor without customer notification  
Change item :  Design  Raw Material  Wafer FAB  Assembly  Testing  Packing  Others

**Affected Product(s) :**

W25Q64FWBYIG , W25Q64FWSSIF , W25Q64FWSSIG , W25Q64FWSSIQ , W25Q64FWZEIG , W25Q64FWZPIF , W25Q64FWZPIG , W25Q64FWZPIQ , W25Q64FWXGIG

**Description of Change(s)**

The W25Q64JW 64Mb SpiFlash® Memories use Winbond’s F58 Flash technology. It is function-compatible with W25Q64FW F58 devices offering improved performance, features and availability.

- a) Command backward compatible with W25Q64FW (same Superset Instruction Set)
- b) Clock operation up to 133MHz
- c) Support DTR with Max. frequency up to 66MHz
- d) SPI with Single / Dual / Quad / QPI
- e) Flexible architecture with 4KB sectors
- f) Support low power consumption compared to W25Q64FW
- g) Support fast programing compared to W25Q64FW

**Reason for Change(s) :**

Improve features, cost, and keep command backward compatible with W25Q64FW (same Superset Instruction Set).

**Impact of Change(s) : ( positive & negative )**

Form : Change No change except WLCSP package form. (Please refer to attachment I)

Fit : Change No change except WLCSP package form. (Please refer to attachment I)

Function : No Concern (Please refer to attachment II)

Reliability : No Concern (Please refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV)

**Qualification Plan/ Results :**

Based on Winbond W25Q64JW Serial Flash Reliability report, the new product meets our criteria and no quality concern(refer to Attachment III in details)



**Implementation Plan :**

Please refer to attachment V for details.

Date Code: \_\_\_\_\_ onward     Lot No: \_\_\_\_\_ onward     Proposed first ship date: Please refer to attachment V.

**Originator: (QA)**

*Hyhuang*

**Approval: (QA Dept. Manager)**

*YH Cheng*

**Approval: (QRA Director)**

*Kevin Chen*

**Contact for Questions & Concerns**

Name: Betty Huang TEL:886-3-5678168 (ext.76549) FAX: 886-3-5796124  
Address : No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung City 42881,Taiwan  
E-mail: Hyhuang8@winbond.com

**Customer Comments:**

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

**Major change:**  Approval     Disapproval     Conditional Approval : \_\_\_\_\_.

**Minor change with customer notification:**  Recognition

**Minor change without customer notification:**  Approval     Disapproval

Conditional Approval : \_\_\_\_\_

Comment:

Date: \_\_\_\_\_

Dept. name: \_\_\_\_\_

Person in charge: \_\_\_\_\_



### Winbond Electronics Corporation

No.539, Sec.2, Wenxing Rd., Jhubei City,  
Hsinchu County 30274, Taiwan R.O.C.

## Product Obsolescence Notice

### W25Q64JW SpiFlash Memories

Notification Date: Dec,20, 2019

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q64FW SpiFlash memory, and replace it with the W25Q64JW. Replacement part numbers are listed below:

Winbond Current PN (58nm F-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25Q64FWBYIG	W25Q64JWBYIQ W25Q64JWBYIM
W25Q64FWSSIG W25Q64FWSSIQ W25Q64FWSSIF	W25Q64JWSSIQ W25Q64JWSSIM
W25Q64FWZEIG	W25Q64JWZEIQ W25Q64JWZEIM
W25Q64FWZPIG W25Q64FWZPIQ W25Q64FWZPIF	W25Q64JWZPIQ W25Q64JWZPIM
W25Q64FWXGIG	W25Q64JWXGIQ W25Q64JWXGIM

For WLCSP, please contact our sales to get the different POD Dimension.

The W25Q64JW device features:

#### Features

- a) Command backward compatible with W25Q64FW (same Superset Instruction Set)
- b) Clock operation up to 133MHz
- c) Support DTR with Max. frequency up to 66MHz
- d) SPI with Single / Dual / Quad / QPI
- e) Flexible architecture with 4KB sectors
- f) Support low power consumption compared to W25Q64FW
- g) Support fast programing compared to W25Q64FW

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q64FW	Jan./01/ 2020	Jul./01/ 2020	Jan./01/ 2021	W25Q64JW	ready	Nov./01/ 2019

Jooweon Park  
Technology Executive  
Flash Product Marketing Center